

METHOD AND APPARATUS FOR MACHINING SUBSTRATE

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ABSTRACT OF THE DISCLOSURE

10 In a substrate machining method for machining a
substrate, there are provided a substrate machining
method in which a disk-like blade is rotated to cut the
substrate from its one surface, and the cut surfaces of
the substrate, which are positioned in the vicinity of
the other surface of the substrate, are irradiated with
laser light; and a substrate machining apparatus which
15 carries out the substrate machining method. The entirety
of the cut surfaces of the substrate may be irradiated
with the laser light. The laser may be a YAG laser or a
CO₂ laser. Further, a dicing tape may be adhered to the
other surface of the substrate, and the laser light may
20 be irradiated after cutting only the substrate and
expanding the dicing tape. Modified layers are formed by
an irradiation of the laser light, so that dice are
prevented from being broken in an assembling operation of
the dice.